

Title (en)

Process for selective deposition of a metal layer

Title (de)

Verfahren zur selektiven Abscheidung einer Metallschicht

Title (fr)

Procédé de dépôt sélectif d' une couche métallique

Publication

**EP 0926262 B1 20030326 (DE)**

Application

**EP 98121020 A 19981105**

Priority

DE 19748888 A 19971105

Abstract (en)

[origin: DE19851101A1] Site selective coupling of multi-atom polar compound (I) to surface of a polymer substrate where regions of the surface are treated with electromagnetic radiation. Components in the base material of the polymer are converted to reactive centers and brought into contact with a liquid solution of the polar compound (I) to couple (I) to the reactive centers. An Independent claim is included for a process for the selective deposition of a metal layer onto the surface of a polymer substrate comprising: (A) irradiating the areas of the surface to be coated with electromagnetic radiation to produce reactive centers; (B) fixing the reactive functional groups on the surface with a noble metal compound by contact with a solution of one or more noble metal compounds (II); (C) depositing the metal layer in an electroless plating bath.

IPC 1-7

**C23C 18/16**

IPC 8 full level

**C23C 18/16** (2006.01)

CPC (source: EP)

**C23C 18/1605** (2013.01); **C23C 18/1608** (2013.01); **C23C 18/1612** (2013.01); **C23C 18/30** (2013.01)

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